

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-28 (Canceled).

Claim 29 (Previously Presented): A semiconductor apparatus comprising:
a semiconductor device;
a plurality of lead wires connected to a plurality of connecting electrodes formed on
said semiconductor device;
at least a pair of dummy lead wires that are not electrically connected to said
semiconductor device and do not include an outer lead portion for electrically connecting said
semiconductor device to an external circuit of said semiconductor device, tip portions of said
at least the pair of dummy lead wires extending over the semiconductor device;
an insulating film having an opening portion configured to accommodate said
semiconductor device and to support said plurality of lead wires connected to the plurality of
connecting electrodes of the semiconductor device and said at least the pair of dummy lead
wires, said opening portion having a plurality of sides that define a perimeter of said opening
portion; and
a resin molding configured to cover a connecting portion between tip portions of the
plurality of lead wires and the plurality of connecting electrodes and the tip portions of said at
least the pair of dummy lead wires within the opening portion of said insulating film,
wherein one and the other of said at least the pair of dummy lead wires are provided
on one side and an opposite side of said plurality of sides of said insulating film, respectively,
each of the one and the other of said at least the pair of dummy lead wires being arranged in
corresponding first and second spaces defined by first and second two adjacent lead wires of

said plurality of lead wires, respectively, so that a length of each of said first and second spaces is at least twice a minimum pitch between adjacent lead wires of said plurality of lead wires, said first two adjacent lead wires being provided on said one side of said insulating film to define said first space on said one side of said insulating film, and said second two adjacent lead wires being provided on said opposite side of said insulating film to define said second space on said opposite side of said insulating film.

Claim 30 (Canceled).

Claim 31 (Previously Presented): A semiconductor apparatus according to claim 29, wherein a semiconductor chip in which the semiconductor device is formed has a thickness of approximately 50 μm .

Claims 32-36 (Canceled).

Claim 37 (Currently Amended): A semiconductor apparatus according to claim 29, wherein ~~tip portions of the at least a pair of dummy wires extend over the semiconductor device and the tip portions of the at least a pair of dummy wires are connected to each other over the semiconductor device.~~